

Quality Assurance Procedure

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QAP004 Rev. A

4/21/99

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In House Repair Procedure

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A	Initial Release	4/21/99	Dior Wu

Originator

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1.0 PURPOSE

1.1 The purpose of this procedure is to provide a uniform guideline for assemblies or bare fabs which are repaired "In House" at Meritronics.

2.0 SCOPE

2.1 This procedure governs all "In House" repairs of production material at Meritronics customer.

3.0 REFERENCES

- 3.1 IPC-R-700 Guidelines for Modification, Rework, and Repair of Printed Boards and Assemblies
- 3.2 IPC-A-610 Acceptability of Electronic Assemblies
- 3.3 SOP10 Supplier Selection and Qualification
- 3.4 SOP23 Control of Non-Conforming Materials

4.0 <u>DEFINITIONS</u>

4.1 Repair: Correction on non-conforming material using specialized techniques to ensure that the requirements of form, fit, function, and inter changability and service are met.

5.0 <u>RESPONSIBILITIES</u>

- 5.1 It is the responsibility of Meritronics Quality Assurance to coordinate repair of all material covered by the scope of this procedure. This shall be accomplished by participation in the Material Review Board (MRB) process.
- 5.2 It is the responsibilities of all affected departments to implement the direction of MRB as it relates to in-house repair.

6.0 EQUIPMENT

6.1 As called out in IPC-R-700.

7.0 <u>MATERIALS</u>

7.1 As called out in IPC-R-700.



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8.0 RECORDS

- 8.1 The total retention period for the documents listed by Meritronics Corporation, is indicated on the Master Forms Listing under the column heading, Record Retention. When the records are no longer in an active status they will be forwarded to Document Control and filed/maintained in accordance with SOP 29.
- 8.2 It is the responsibility of Manufacturing to maintain all records of repair as part of the MRB process.

9.0 **PROCEDURE**

- 9.1 All assemblies or bare fabs considered for repair must be dispositioned as such by the Meritronics Material Review Board. Customer concurrence may be required in order to reach such a decision. If this is the case, Quality Assurance and/or Program Manager will coordinate the effort.
- 9.2 All repairs will be accomplished, if possible, in accordance with IPC-R-700. If IPC-R-700 guidelines do not adequately address the situation, a non-standard repair method may be documented by Manufacturing Engineering as part of the repair process.
- 9.3 In-house repairs
 - 9.3.1 Repair methodology will be documented as part of the MRB process and will be performed accordingly.
 - 9.3.2 All fabs and assemblies repaired shall be subject to review by Manufacturing Engineering and Quality Assurance prior to being returned to the manufacturing process. The material may or may not be subject to test, depending on the nature of the rework.
- 9.4. Any forms of identification (labels, tags, etc.) placed on the assemblies shall be removed after the repairs have been completed and accepted during the repair inspection process prior to being returned to the manufacturing process.
- 9.5 Customer concurrence
 - 9.5.1 Any customer concurrence required on the use of any repaired material shall be coordinated by Quality assurance and/or Program Manager.